

L Number	Hits	Search Text	DB	Time stamp
3	689	(anodic\$4 adj bond\$3) and ((ltcc or ceramic) and silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:28
4	1411651	semiconduct\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 13:19
5	512	((anodic\$4 adj bond\$3) and ((ltcc or ceramic) and silicon)) and semiconduct\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 13:54
6	50763	hermetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 13:54
7	121	((anodic\$4 adj bond\$3) and ((ltcc or ceramic) and silicon)) and semiconduct\$3 and hermetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:16
8	2	("6660614").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:16
9	1	ceramic and ("6660614").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:16
10	279	(anodic\$4 adj bond\$3) and (((silicon adj carbide) or sic) and silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:29
11	13	(anodic\$4 adj bond\$3) near7 ((silicon adj carbide) or sic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:47
12	22	4983538.URPN.	USPAT	2004/07/15 14:37
13	0	4983538.URPN. and (anodic\$4 adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:47
14	0	ltcc near3 ((silicon adj carbide) or sic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:47
15	757	ltcc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:50
16	61	ltcc.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:48
17	26	ltcc and (anodic\$4 adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 14:55

18	2	("6437981").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:00
19	0	pyrex near4 ltcc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:57
20	1	imego.as. and ((anodic\$4 adj bond\$3) and ((ltcc or ceramic) and silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:59
21	2	imego.as. and ltcc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:58
22	1	(imego.as. and ltcc) not (imego.as. and ((anodic\$4 adj bond\$3) and ((ltcc or ceramic) and silicon)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:59
23	0	((imego.as. and ltcc) not (imego.as. and ((anodic\$4 adj bond\$3) and ((ltcc or ceramic) and silicon)))) and (anodic\$4 adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:59
24	1	imego.as. and hermetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:00
25	1369	galvanic and anodic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:01
26	3290	(persson or bergstedt).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:02
27	2395	anodic\$4 adj bond\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:02
28	3	((persson or bergstedt).in.) and (anodic\$4 adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:03
29	1	((persson or bergstedt).in.) and (anodic\$4 adj bond\$3)) and ltcc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:03

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1	1462	(electrostatic or (electro adj static)) adj bond\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:47
2	296	ltcc and (silicon or si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:39
3	0	((electrostatic or (electro adj static)) adj bond\$3) and (ltcc and (silicon or si))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:39
4	130081	ceramic and (silicon or si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:39
5	194	((electrostatic or (electro adj static)) adj bond\$3) and (ceramic and (silicon or si))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:49
6	25	Chung.in. and (((electrostatic or (electro adj static)) adj bond\$3) or (anodic\$4 adj bond\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:07
7	7	(Chung.in. and (((electrostatic or (electro adj static)) adj bond\$3) or (anodic\$4 adj bond\$3))) and (ceramic and (silicon or si))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:09
8	4	"6537892"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:09
9	3747	((electrostatic or (electro adj static)) adj bond\$3) or (anodic\$4 adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:48
10	862	((electrostatic or (electro adj static)) adj bond\$3) or (anodic\$4 adj bond\$3)) and (ceramic and (silicon or si))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 17:48
11	118	semiconduct\$3 and (((electrostatic or (electro adj static)) adj bond\$3) and (ceramic and (silicon or si)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 18:01
12	2	("5,443,890").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 18:03
13	1	((("5,443,890").PN.) and (((electrostatic or (electro adj static)) adj bond\$3) or (anodic\$4 adj bond\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 18:05

L Number	Hits	Search Text	DB	Time stamp
1	197	ltcc and ca	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:24
2	3747	(anodic\$4 adj bond\$3) or (electrostatic or (electro adj static)) adj bond\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:27
3	4	(ltcc and ca) and ((anodic\$4 adj bond\$3) or (electrostatic or (electro adj static)) adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:27
4	3827	(anodic\$4 adj bond\$3) or ((electrostatic or (electro adj static)) adj bond\$3) or (field adj assist\$3 adj bond\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:28
5	757	ltcc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:28
6	26	((anodic\$4 adj bond\$3) or ((electrostatic or (electro adj static)) adj bond\$3) or (field adj assist\$3 adj bond\$3)) and ltcc	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:28